



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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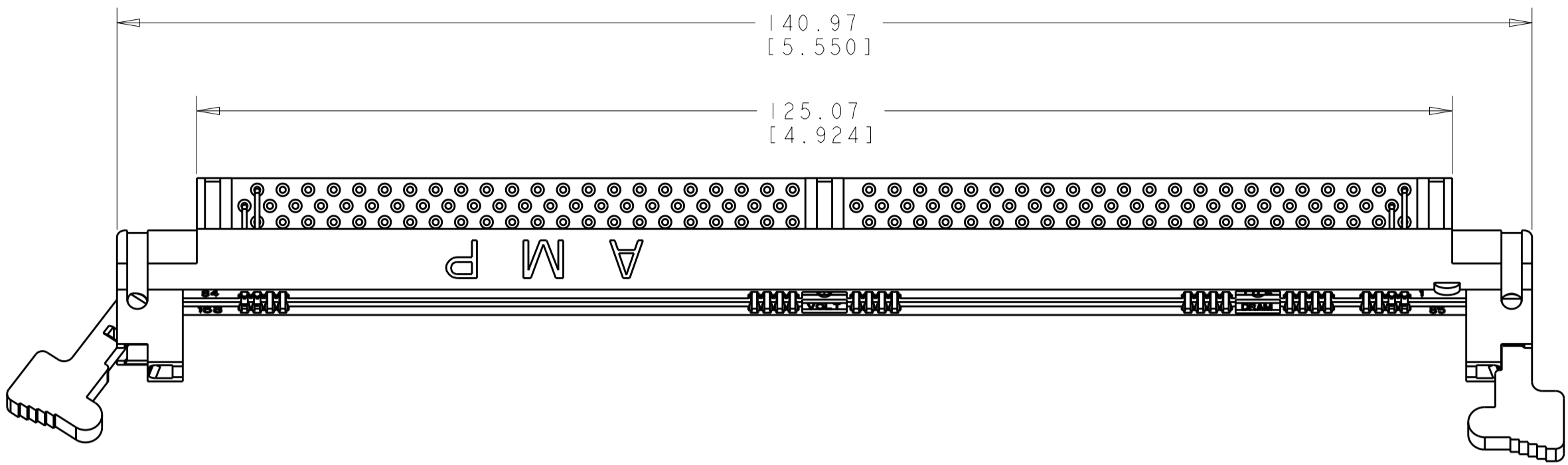
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

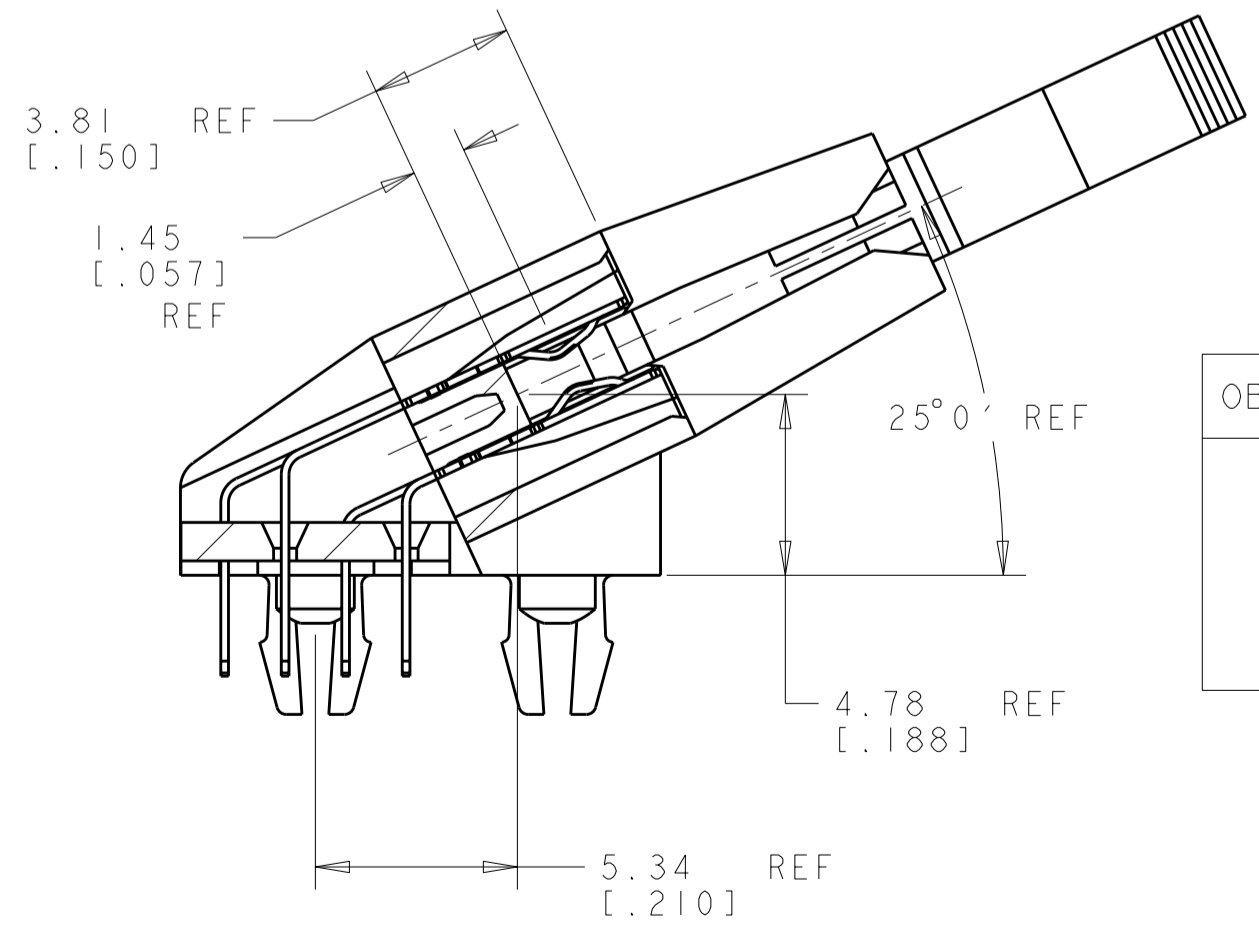
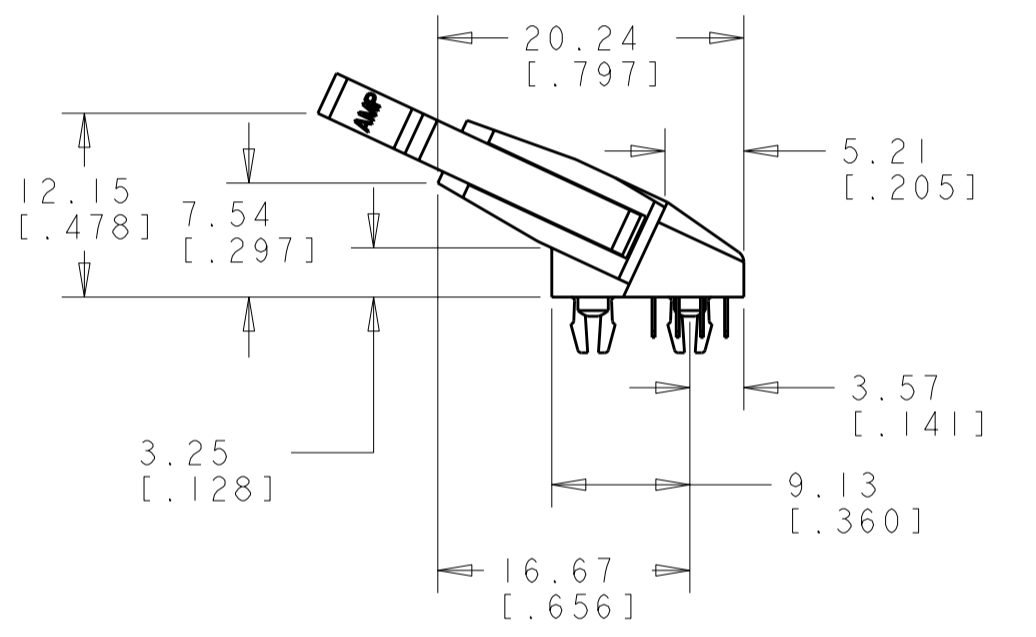
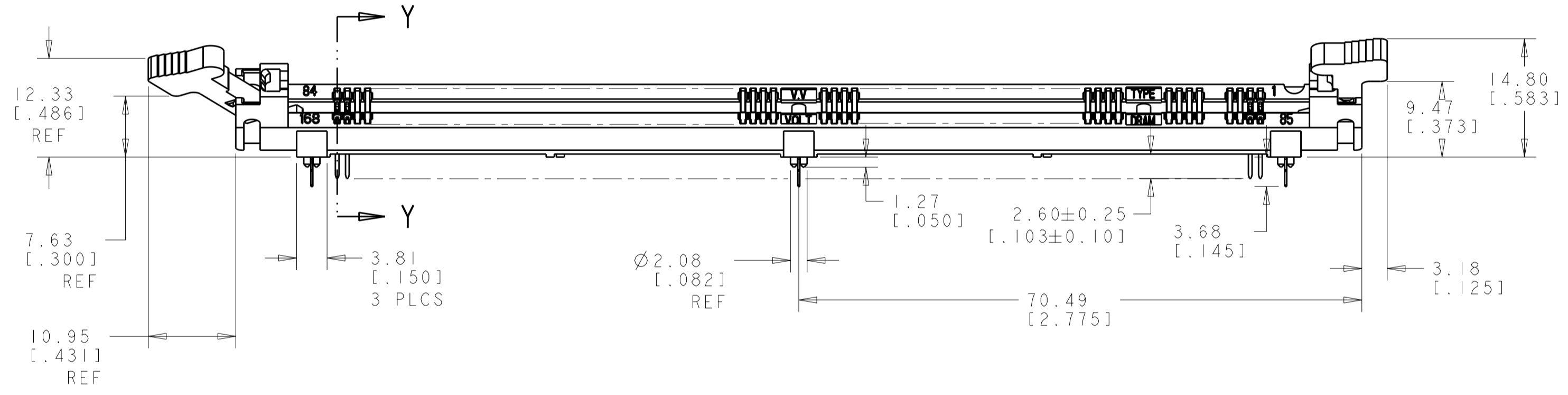


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LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD		
	B	REVISED ECR-06-000966	19JAN06	LZ	SY		
	C	ECR-11-013206	27JUN2011	D.P	C.W		



- NOTES:
- MATERIAL:
HOUSING AND EJECTOR:
HIGH TEMPERATURE NYLON
CONTACT:
PHOSPHOR BRONZE
 - FINISH:
CONTACT AREA:
0.00076[.000030] MIN THICK GOLD OVER
0.00381[.000150] MIN THICK NICKEL
SOLDERTAIL:
0.00381[.000150] MIN THICK MATTE TIN OVER
0.00064[.000025] MIN THICK NICKEL
 - MODULE BOARD PADS:
FOR OPTIMUM PERFORMANCE PADS SHOULD BE SMOOTH AND FLAT
PADS TO BE PLATED WITH:
0.00102[.000040] MIN THICK GOLD OVER
0.00127[.000050] MIN THICK NICKEL
 - FINISH:
CONTACT AREA:
0.00076[.000030] MIN THICK GOLD OVER
0.00381[.000150] MIN THICK NICKEL
SOLDERTAIL:
GOLD FLASH OVER 0.00064[.000025] MIN THICK NICKEL



SECTION Y - Y
SCALE 5:1

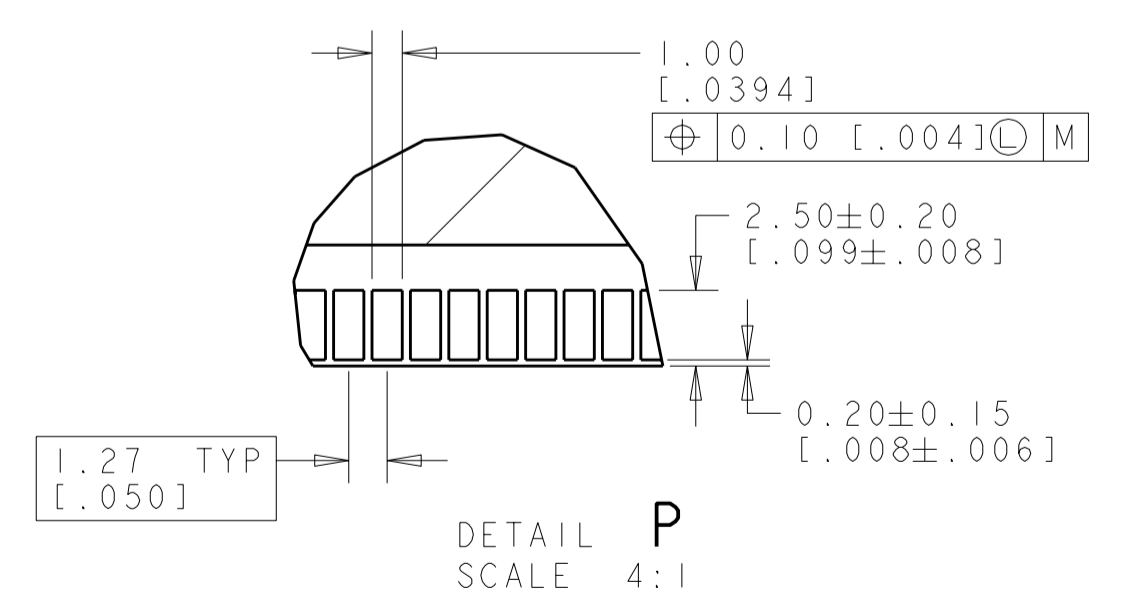
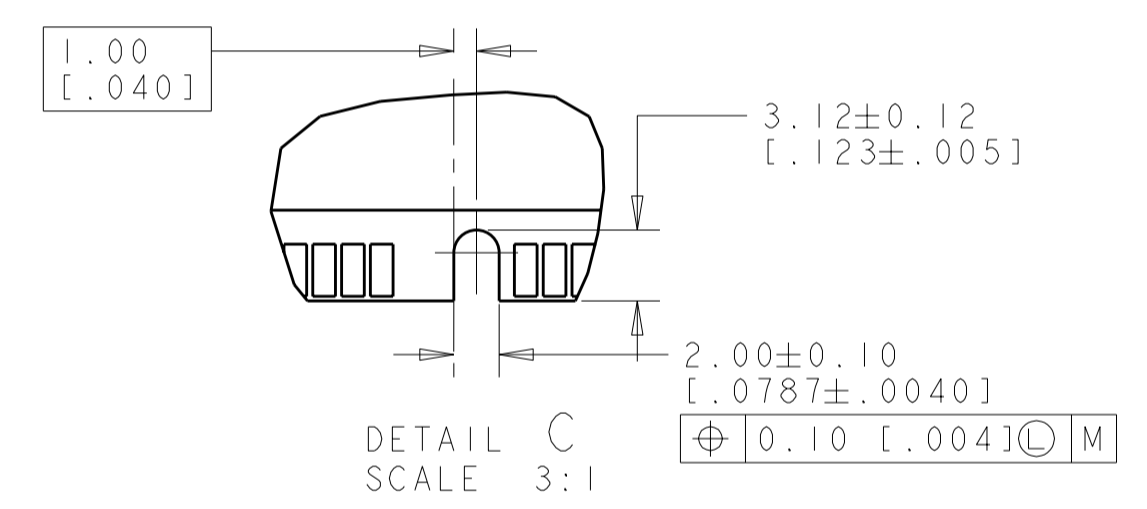
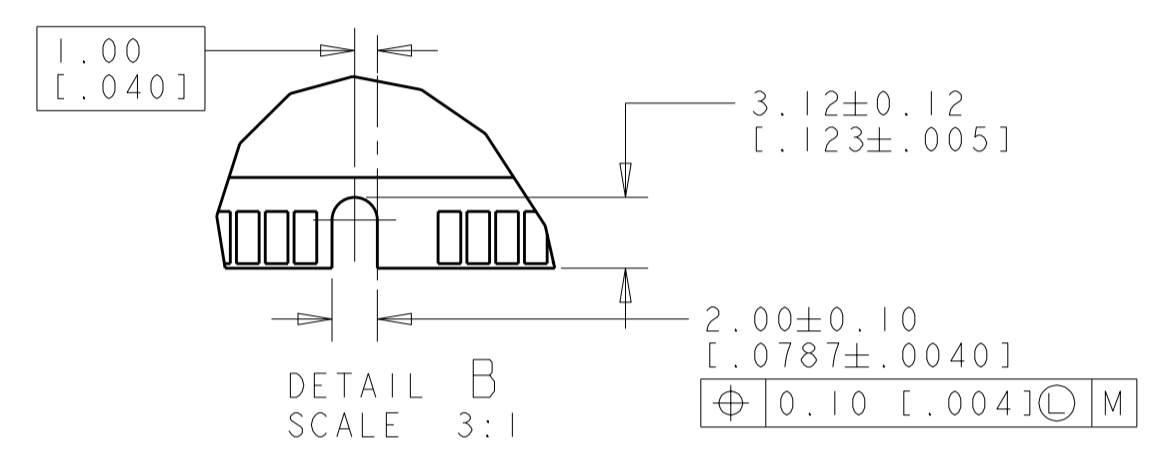
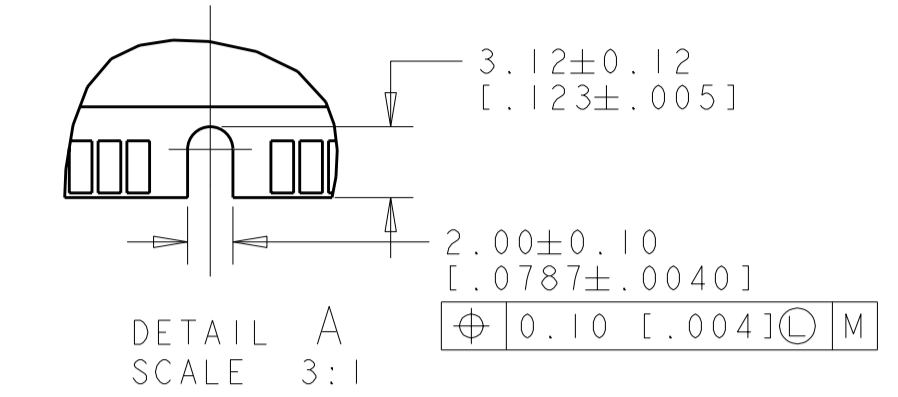
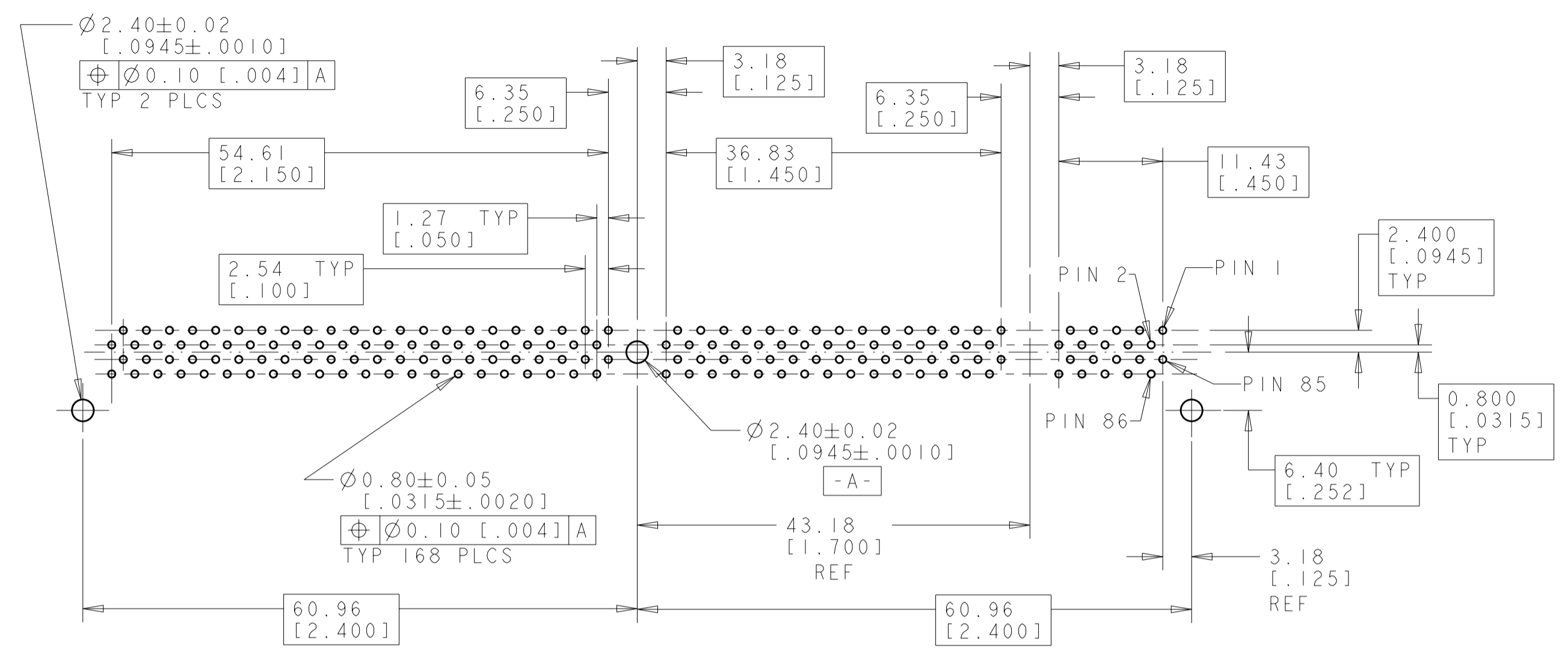
OBSOLETE	KEY #1	KEY #2	PART DESCRIPTION	PART NUMBER	
	4	DETAIL C	DETAIL A	NON-BUFFERED DRAM, 3.3 VOLT	2-5390195-6
	2	DETAIL C	DETAIL A	NON-BUFFERED DRAM, 3.3 VOLT	5390195-6
	2	DETAIL A	DETAIL A	STD DRAM, 3.3 VOLT	5390195-4
	FINISH	KEY #1	KEY #2	PART DESCRIPTION	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		DWN M. YEOMANS 13JAN05	Tyco Electronics Corporation SH/CN GuiPingRD 668#	
DIMENSIONS: mm [INCHES]		CHK M. YEOMANS 13JAN05	NAME LOW PROFILE (25 DEG) DIMM 2P SOCKET CENTER METAL BOARD LOCK 168 POSITION	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.13[.005] 3 PLC ± 4 PLC ± ANGLES ± FINISH		APVD S. BURKHOLDER 13JAN05	PRODUCT SPEC APPLICATION SPEC WEIGHT CUSTOMER DRAWING	
MATERIAL		SIZE A260779	CAGE CODE C-5390195	RESTRICTED TO -
AMP 1471-9 REV 31MAR2000		SCALE 1:1	SHEET 1	OF 3 REV C

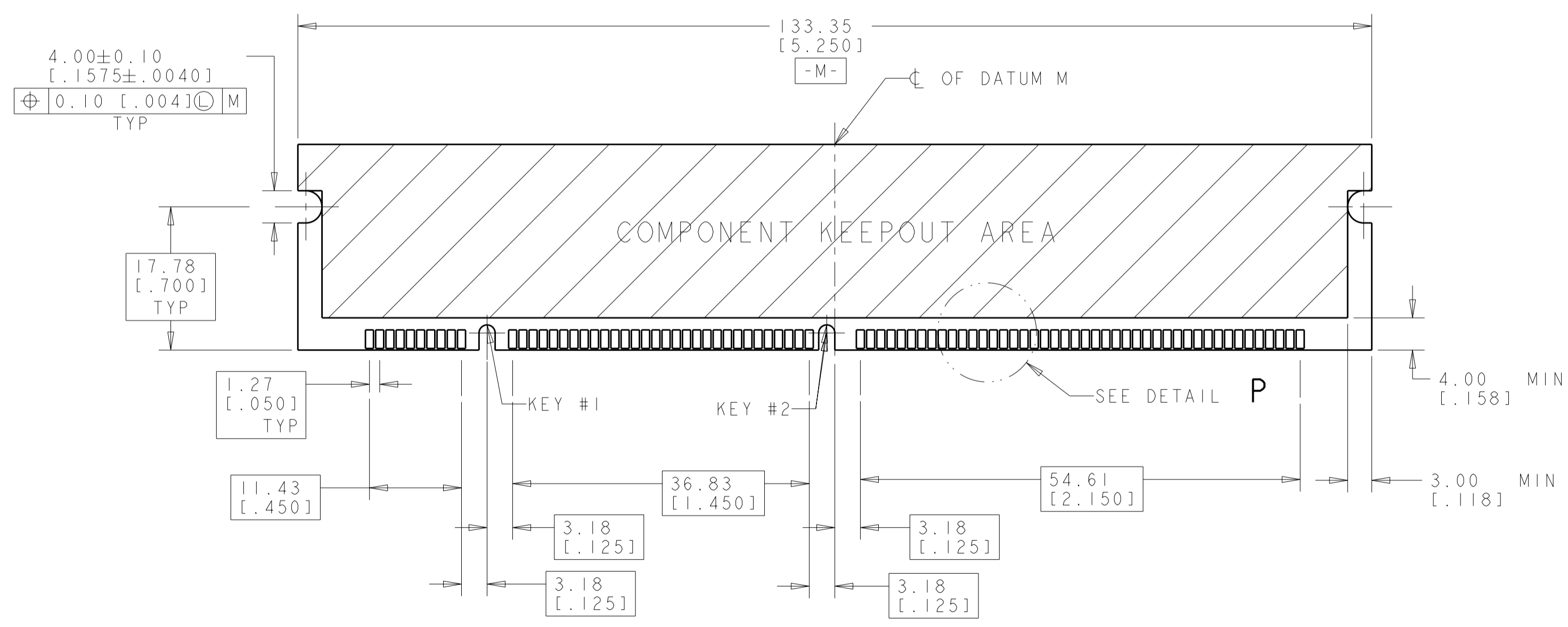
5390195

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LOC	DIST	REVISIONS				
P	LTR	DESCRIPTION	DATE	DWN	APVD	
ES	00	SEE SHEET 1				



RECOMMENDED CIRCUIT BOARD HOLE LAYOUT



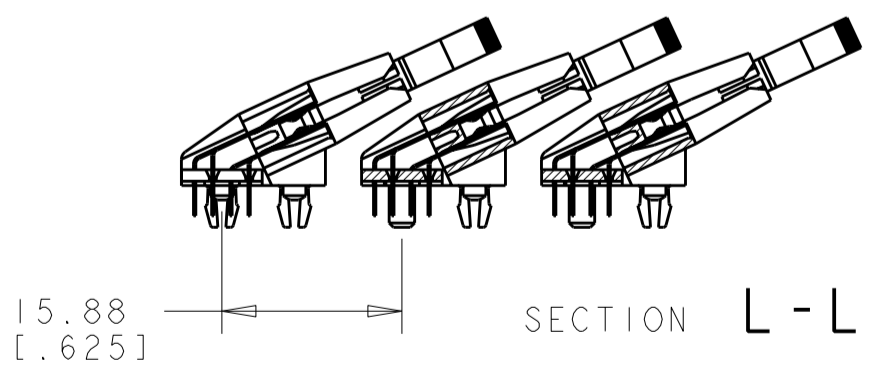
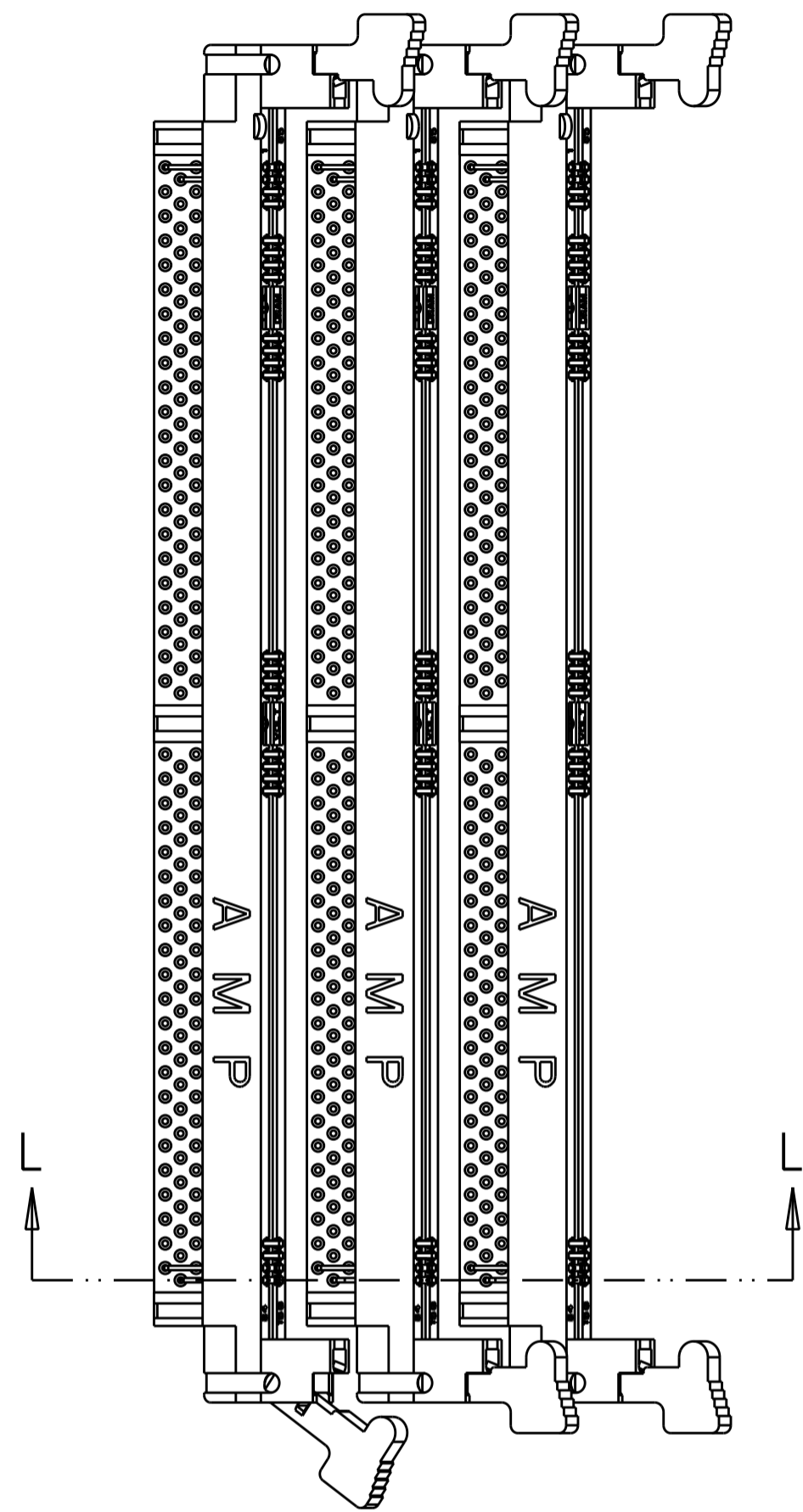
RECOMMENDED MODULE LAYOUT

SEE JEDEC SPEC. MO-161 FOR COMPLETE MODULE DETAILS
 1.27 ± 0.10 [.050 ± 0.004] THICK ACROSS CONTACT PADS

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DIMENSIONS: mm [INCHES]		CHK M. YEOMANS 13 JAN 05	NAME LOW PROFILE (25 DEG) DIMM 2P SOCKET CENTER METAL BOARD LOCK 168 POSITION	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.13 [.005] 3 PLC ± 4 PLC ± ANGLES ± FINISH		APVD S. BURKHOLDER 13 JAN 05	PRODUCT SPEC APPLICATION SPEC WEIGHT CUSTOMER DRAWING	
MATERIAL		SCALE 4:1		RESTRICTED TO
		A200779C-5390195		SHEET 2 OF 3 REV C

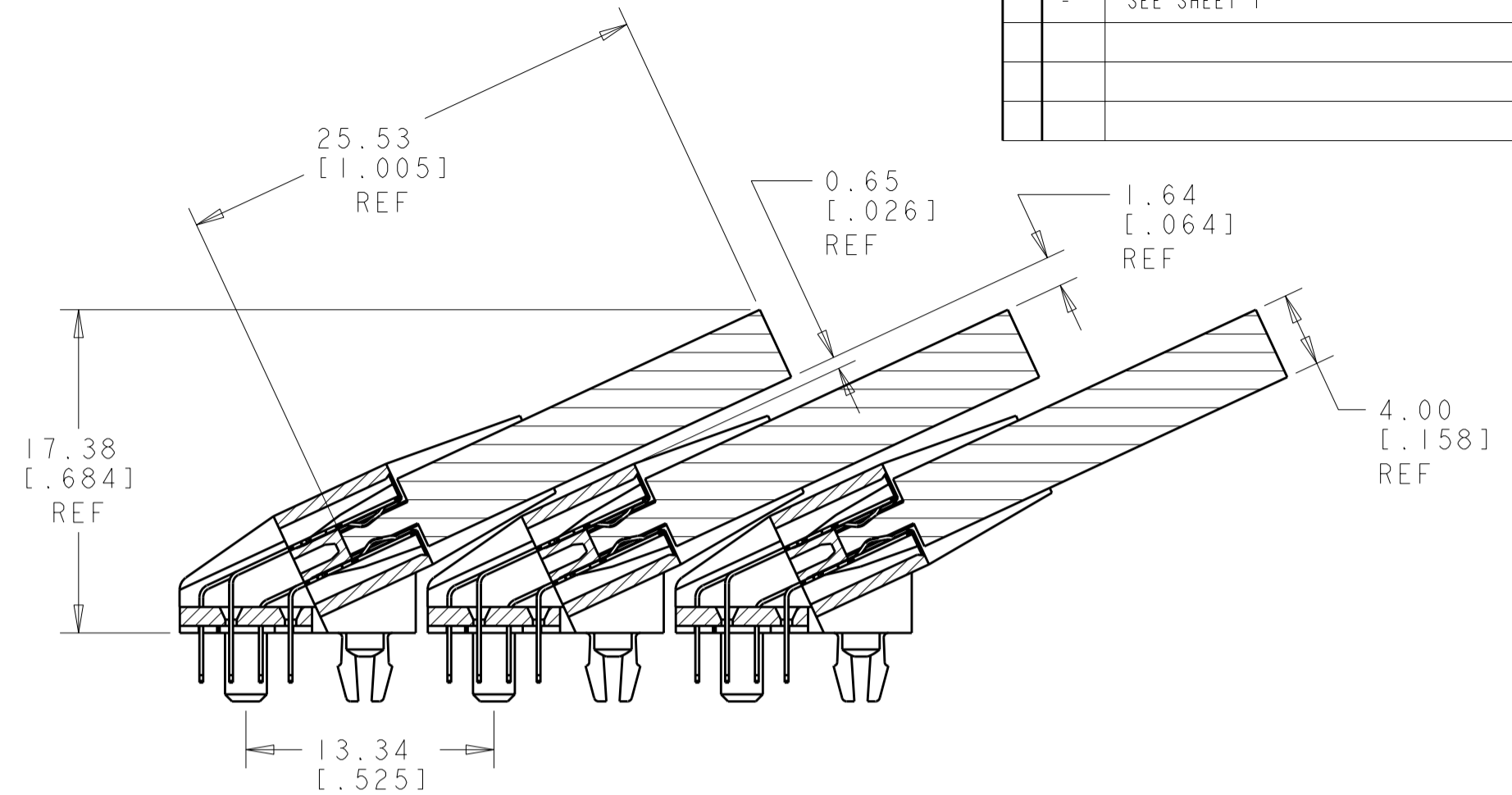
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LOC	DIST	REVISIONS			
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ES	00	SEE SHEET 1			



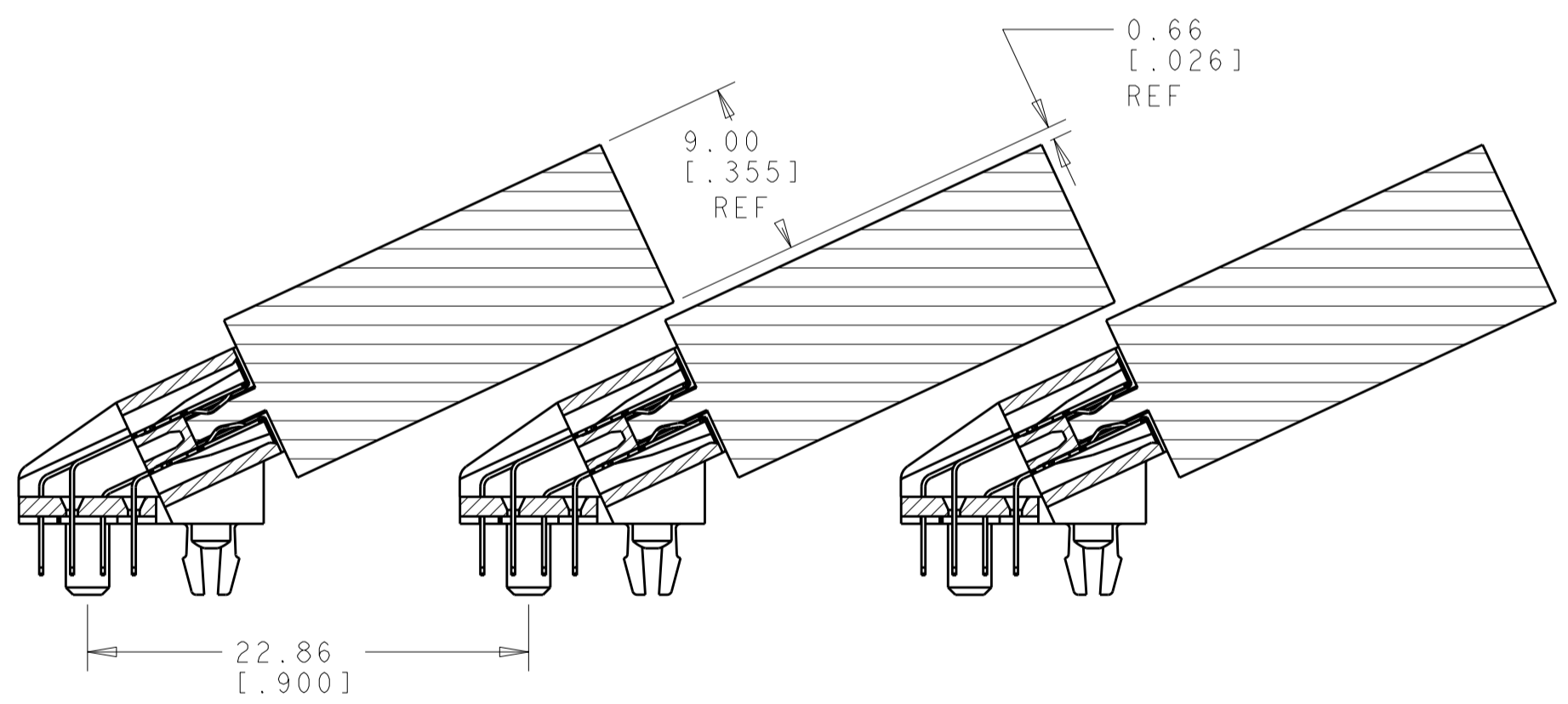
MINIMUM REPAIRABLE SOCKET TO SOCKET SPACING

WITH THE MODULES REMOVED, SOCKETS ON 15.88 [0.625] OR GREATER SPACING CAN BE INDIVIDUALLY UNSOLDERED FROM THE BOARD AND REMOVED IF NECESSARY.



MINIMUM SOCKET TO SOCKET SPACING

WITH A 4.00 [0.158] WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 13.34 [0.525] WILL LEAVE APPROXIMATELY 0.65 [0.026] OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



POSSIBLE SOCKET TO SOCKET SPACING FOR 9MM SOCKET

WITH A 9.00 [0.355] WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 22.86 [0.900] WILL LEAVE APPROXIMATELY 0.66 [0.026] CLEARANCE BETWEEN THE ADJACENT MODULES. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.

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		CHK M. YEOMANS 13JAN05	SH/CN GuiPingRD 668#	
DIMENSIONS: mm [INCHES]		APVD S. BURKHOLDER 13JAN05	NAME LOW PROFILE (25 DEG) DIMM 2P SOCKET CENTER METAL BOARD LOCK 168 POSITION	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.13 [0.005] 3 PLC ± 4 PLC ± ANGLES ± FINISH ±		PRODUCT SPEC - APPLICATION SPEC -	SIZE A20779	DRAWING NO 5390195
MATERIAL -		WEIGHT -	RESTRICTED TO -	
CUSTOMER DRAWING			SCALE 1:1	SHEET 3 OF 3 REV C